

10-Bit μ P-compatible D/A converter

NE5020

DESCRIPTION

The NE5020 is a microprocessor-compatible monolithic 10-bit digital-to-analog converter subsystem. This device offers 10-bit resolution and $\pm 0.1\%$ accuracy and monotonicity guaranteed over full operating temperature range.

Low loading latches, adjustable logic thresholds, and addressing capability allow the NE5020 to directly interface with most microprocessor- and logic-controlled systems.

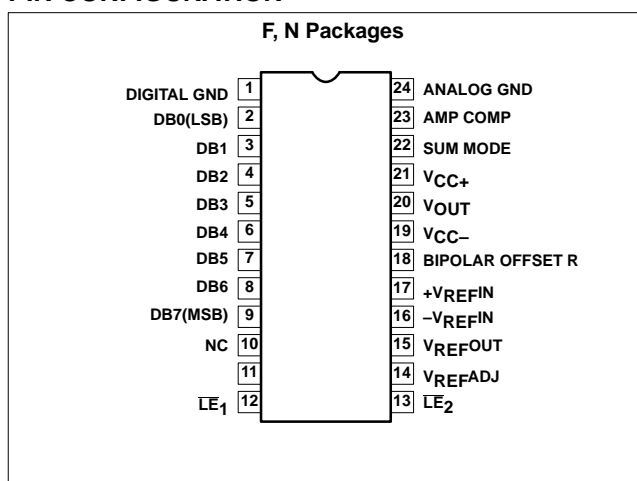
The NE5020 contains internal voltage reference, DAC switches and resistor ladder. Also, the input buffer and output summing amplifier are included. In addition, the matched application resistors for scaling either unipolar or bipolar output values are included on a single monolithic chip.

The result is a near minimum component count 10-bit resolution DAC system.

FEATURES

- 10-bit resolution
- Guaranteed monotonicity over operating range
- $\pm 0.1\%$ relative accuracy
- Unipolar (0V to +10V) and bipolar ($\pm 5V$) output range
- Logic bus compatible
- 5 μ s settling time

PIN CONFIGURATION



APPLICATIONS

- Precision 10-bit D/A converters
- 10-bit analog-to-digital converters
- Programmable power supplies
- Test equipment
- Measurement instruments

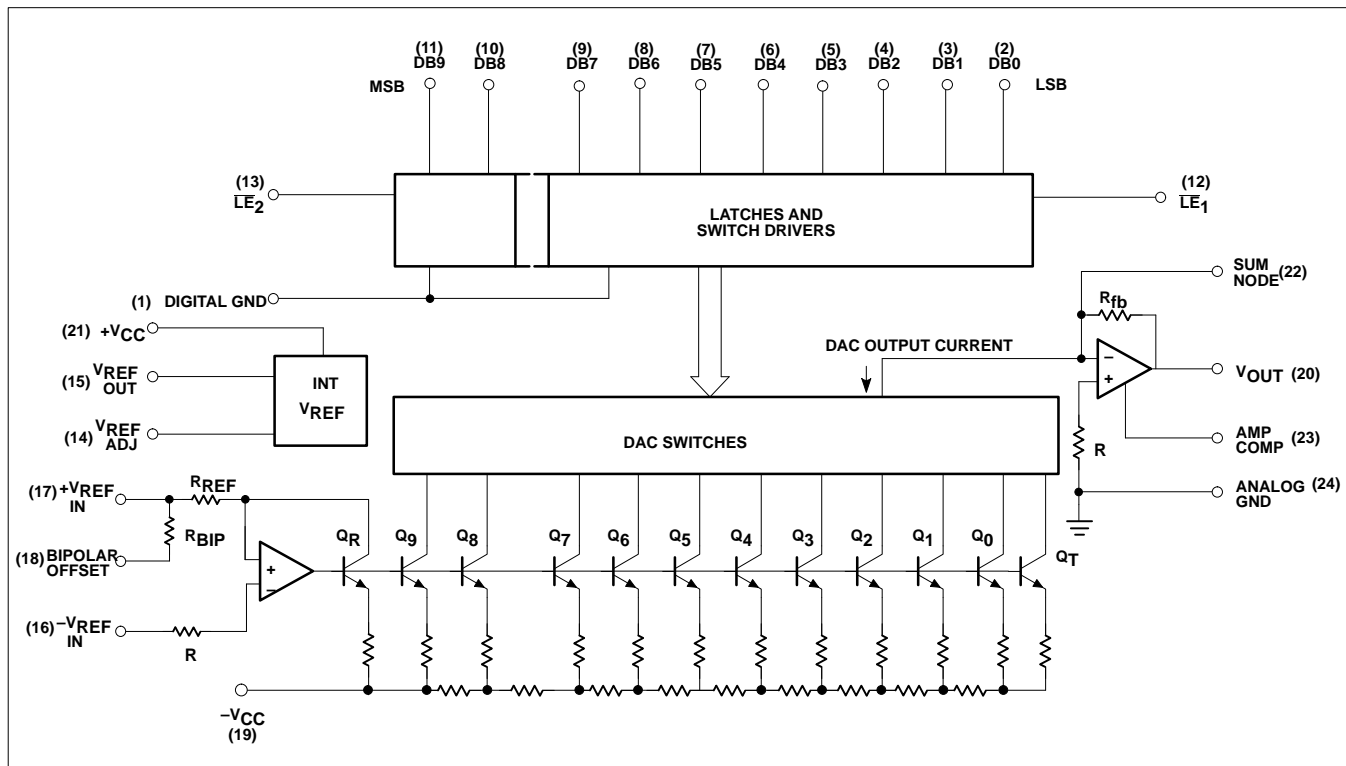
ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #
24-Pin Ceramic Dual In-Line Package (CERDIP)	0 to 70°C	NE5020F	0588B
24-Pin Plastic Dual In-Line Package (DIP)	0 to 70°C	NE5020N	0412A

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NE5020

BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}^+	Positive supply voltage	18	V
V_{CC}^-	Negative supply voltage	-18	V
V_{IN}	Logic input voltage	0 to 18	V
$V_{REF IN}$	Voltage at $V_{REF IN}$ input	12	V
$V_{REF ADJ}$	Voltage at $V_{REF ADJ}$	0 to V_{REF}	V
V_{SUM}	Voltage at sum node	12	V
$I_{REF SC}$	Short-circuit current to ground at $V_{REF OUT}$	Continuous	
$I_{OUT SC}$	Short-circuit current to ground or either supply at V_{OUT}	Continuous	
P_D	Maximum power dissipation $T_A=25^\circ\text{C}$, (still-air) ¹		
	F package	2150	mW
	N package	2150	mW
T_A	Operating temperature range NE5020	0 to +70	$^\circ\text{C}$
T_{STG}	Storage temperature range	-65 to +150	$^\circ\text{C}$
T_{SOLD}	Lead soldering temperature (10 sec. max)	300	$^\circ\text{C}$

NOTES:

- Derate above 25°C at the following rates:
 F package at $17.2\text{mW}/^\circ\text{C}$
 N package at $17.2\text{mW}/^\circ\text{C}$

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NE5020

DC ELECTRICAL CHARACTERISTICS

$V_{CC+}=+15V$, $V_{CC-}=-15V$, $0 \leq T_A \leq 70^\circ C$, unless otherwise specified.¹ Typical values are specified at 25°C.

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
	Resolution Monotonicity Relative accuracy				10 10 ± 0.1	Bits Bits %FS
V_{CC+} V_{CC-}	Positive supply voltage Negative supply voltage		11.4 -11.4	15 -15	16.5 -16.5	V V
$V_{IN(1)}$ $V_{IN(0)}$	Logic "1" input voltage Logic "0" input voltage	Pin 1=0V Pin 1=0V	2.0		0.8	V V
$I_{IN(1)}$ $I_{IN(0)}$	Logic "1" input current Logic "0" input current	Pin 1=0V, $2 < V_{IN} < 18V$ Pin 1=0V, $-5V < V_{IN} < 0.8V$		0.1 -2.0	10 -10	μA μA
V_{FS}	Full-scale output	Unipolar mode, $V_{REF}=5.000V$, all bits high, $T_A=25^\circ C$	9.5		10.5	V
$+V_{FS}$	Full-scale output	Bipolar mode, $V_{REF}=5.000V$, all bits high, $T_A=25^\circ C$	4.75		5.25	V
$-V_{FS}$	Negative full-scale	Bipolar mode, $V_{REF}=5.000V$, all bits low, $T_A=25^\circ C$	-5.25		-4.75	V

NOTES:

1. Refer to Figure 1.

10-Bit μ P-compatible D/A converter

NE5020

DC ELECTRICAL CHARACTERISTICS (Continued)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
V _{ZS}	Zero-scale output	Unipolar mode, V _{REF} =5.000V, all bits low, T _A =25°C	-30		+30	mV
I _{OS}	Output short-circuit current	T _A =25°C V _{OUT} =0V		±15	±40	mA
PSR _{+(OUT)}	Output power supply rejection (+)	V=-15V, 13.5V≤V+≤16.5V, external V _{REF IN} =5.000V		0.001	0.01	%FS/ %VS
PSR _{-(OUT)}	Output power supply rejection (-)	V+=15V, -13.5V≤V-≤-16.5V, external V _{REF IN} =5.000V		0.001	0.01	%FS/ %VS
TC _{FS}	Full-scale temperature coefficient	V _{REF IN} =5.000V		20		ppmFS /°C
TC _{ZS}	Zero-scale temperature coefficient			5		ppmFS/°C
I _{REF} ²	Reference output current				3	mA
I _{REF SC}	Reference short circuit current	T _A =25°C V _{REF OUT} =0V		15	30	mA
PSR _{+REF}	Reference power supply rejection (+)	V=-15V, 13.5V≤V+≤16.5V, I _{REF} =1.0mA		.003	.01	%VR/ %VS
PSR _{-REF}	Reference power supply rejection (-)	V+=15V, -13.5V≤V-≤16.5V,		.003	.01	%VR/ %VS
V _{REF}	Reference voltage	I _{REF} =1.0mA, T _A =25°C	4.9	5.0	5.25	V
TC _{REF}	Reference voltage temperature coefficient	I _{REF} =1.0mA		60		ppm/°C
Z _{IN}	DAC V _{REF IN} input impedance	I _{REF} =1.0mA		5.0		kΩ
I _{CC+}	Positive supply current	V _{CC+} =+15V		7	14	mA
I _{CC-}	Negative supply current	V _{CC-} =-15V		-10	-15	mA
P _D	Power dissipation	I _{REF} =1.0mA, V _{CC} =±15V		255	435	mW

NOTES:

1. Refer to Figure 1.
2. For I_{REF OUT} greater than 3mA, an external buffer is required.

AC ELECTRICAL CHARACTERISTICS¹

V_{CC} = +15V, T_A = 25°C.

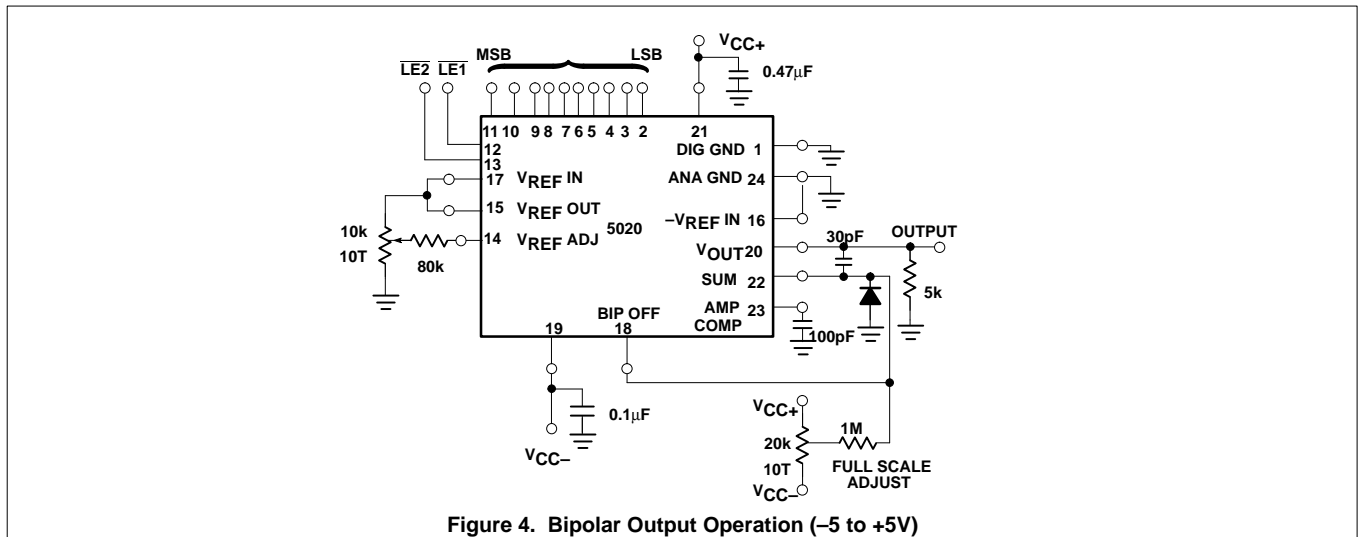
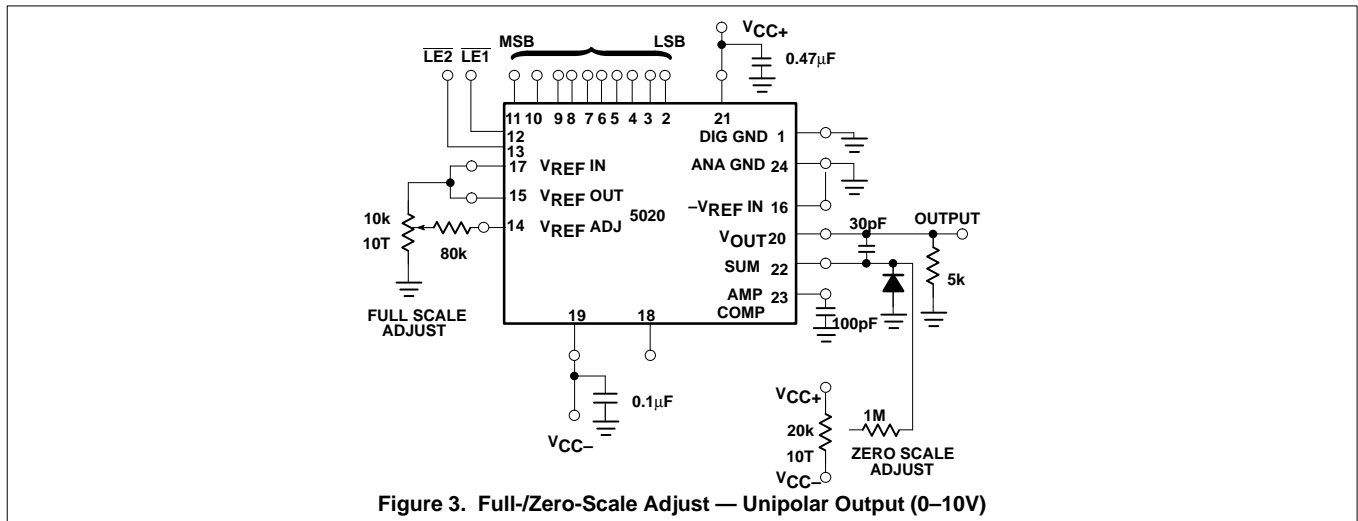
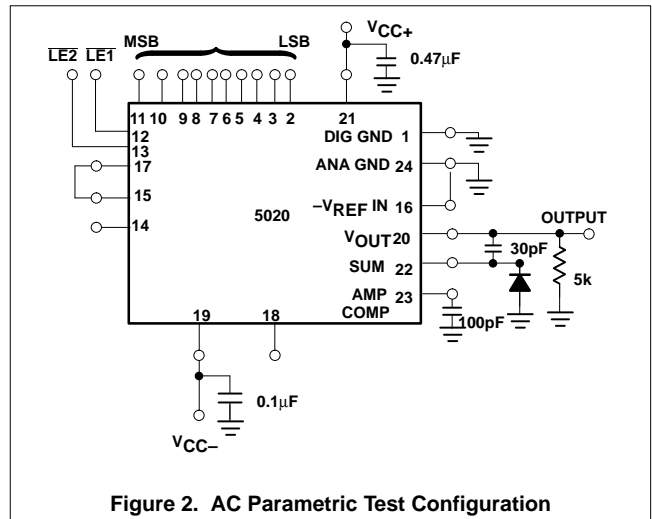
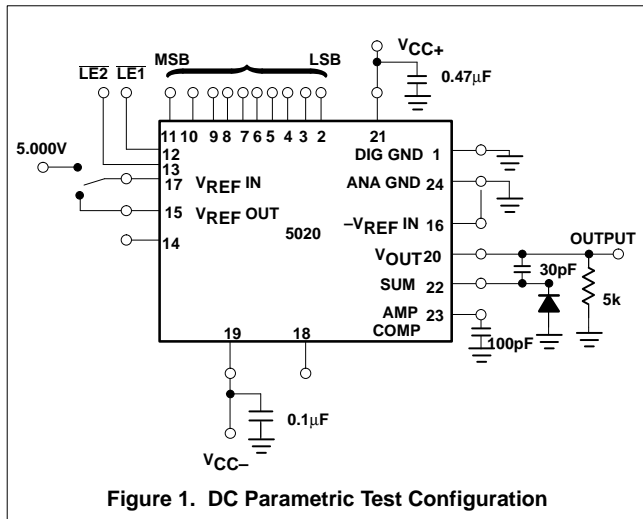
SYMBOL	PARAMETER	TO	FROM	TEST CONDITIONS	LIMITS			UNIT
					Min	Typ	Max	
t _{SLH}	Settling time	±1/2LSB	Input	All bits low-to-high ²		5		μs
t _{SHL}	Settling time	±1/2LSB	Input	All bits high-to-low ³		5		μs
t _{PLH}	Propagation delay	Output	Input	All bits switched low-to-high ²		30		ns
t _{PHL}	Propagation delay	Output	Input	All bits switched high-to-low ³		150		ns
t _{PLSB}	Propagation delay	Output	Input	1 LSB change ^{2,3}		150		ns
t _{PLH}	Propagation delay	Output	LE	Low-to-high transition ⁴		300		ns
t _{PHL}	Propagation delay	Output	LE	High-to-low transition ⁵		150		ns
t _S	Set-up time	LE	Input	1,6	100			ns
t _H	Hold time	Input	LE	1,6	50			ns
t _{PW}	Latch enable pulse width			1,6	150			ns

NOTES:

1. Refer to Figure 2.
2. See Figure 5.
3. See Figure 6.
4. See Figure 7.
5. See Figure 8.
6. See Figure 9.

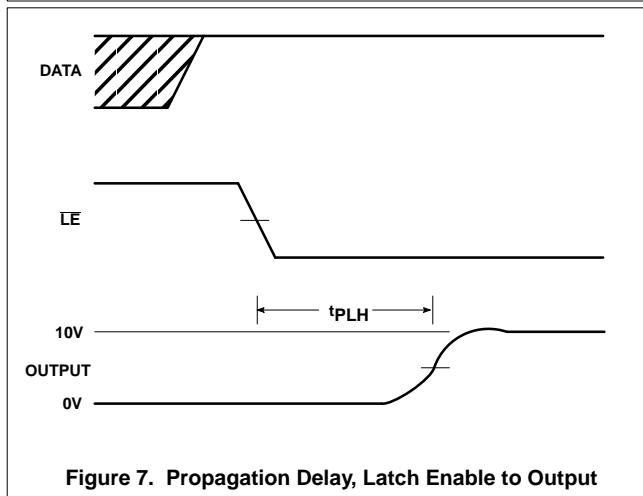
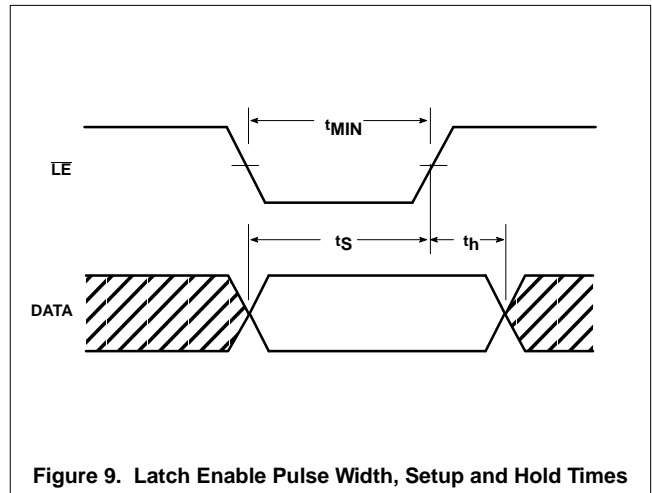
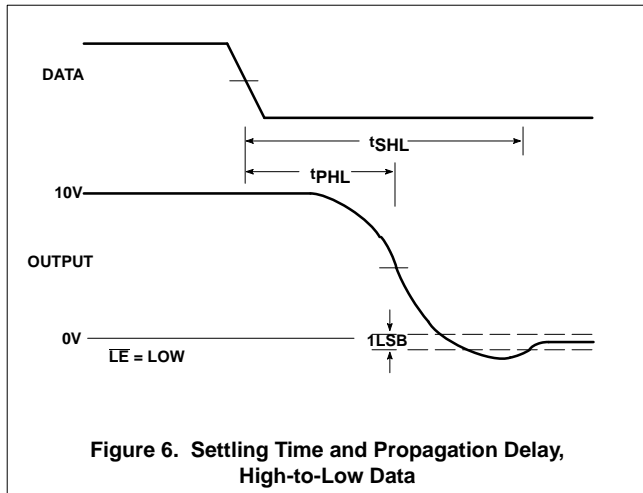
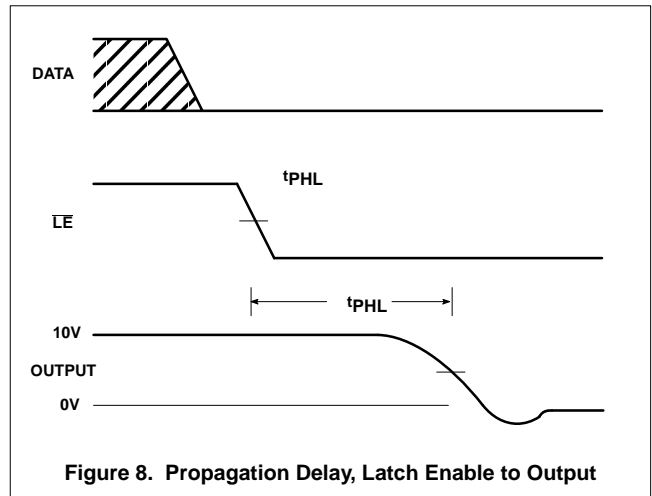
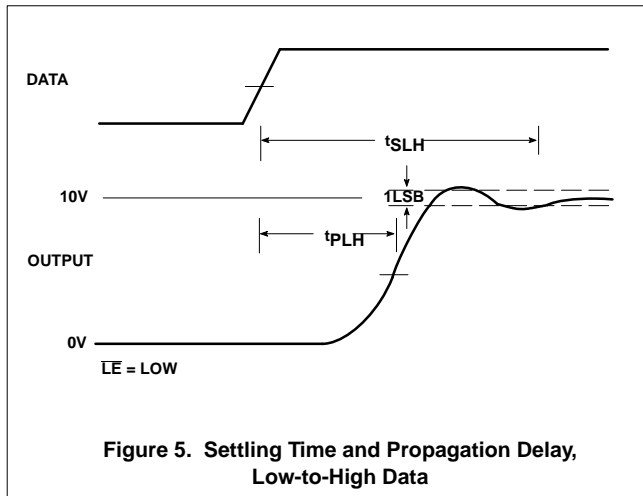
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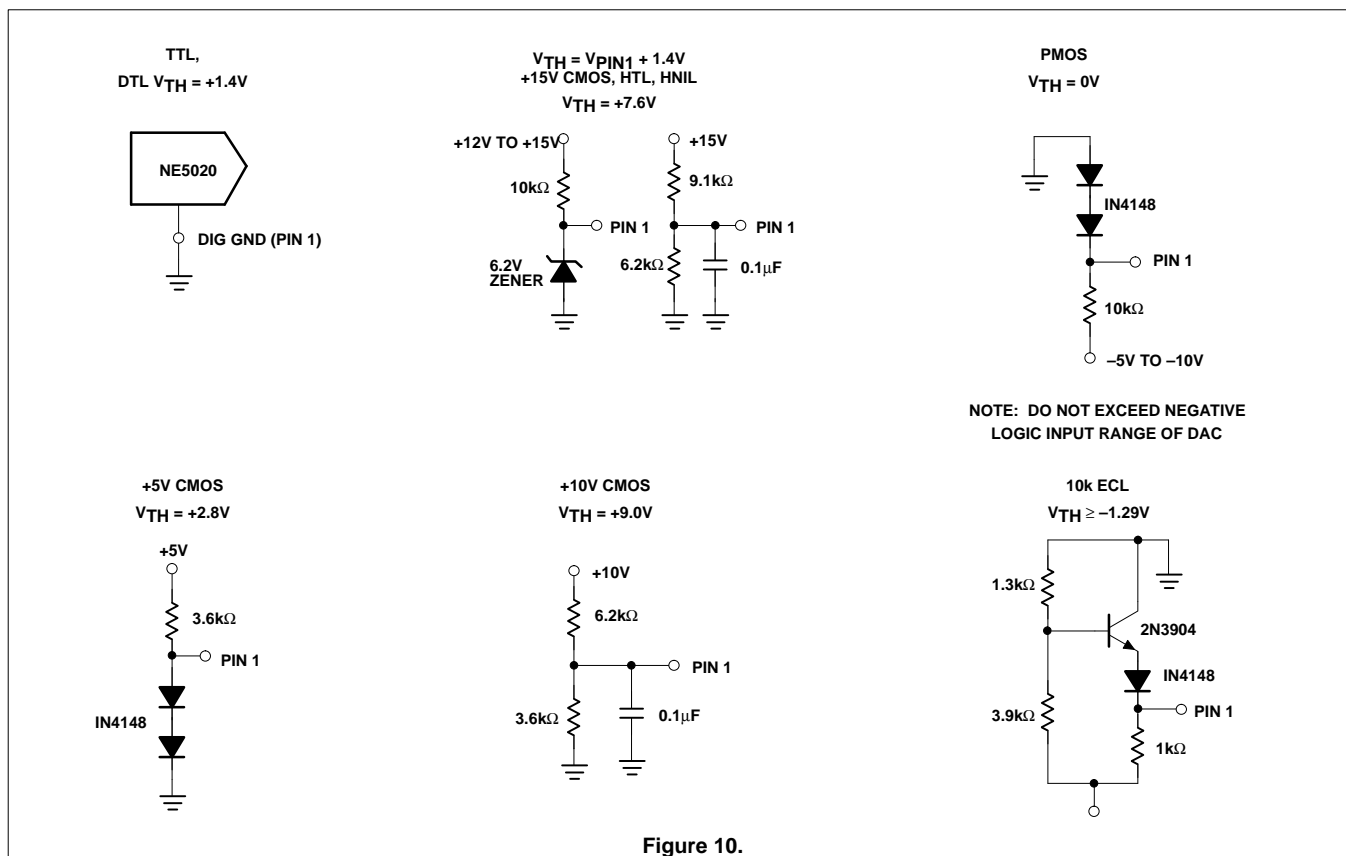


Figure 10.

CIRCUIT DESCRIPTION

The NE5020 provides ten data latches, an internal voltage reference, application resistors, and a scaled output voltage in addition to the basic DAC components (see Block Diagram).

Latch Circuit

Digital interface with the NE5020 is readily accomplished through the use of two latch enable ports (\overline{LE}_1 and \overline{LE}_2) and ten data input latches. \overline{LE}_2 controls the two most significant bits of data (DB9 and DB8) while \overline{LE}_1 controls the eight lesser significant bits (DB7 through DB0). Both the latch enable ports (\overline{LE}) and the data inputs are static- and threshold-sensitive. When the latch enable ports (\overline{LE}) are high (Logic '1') the data inputs become very high impedances and essentially disappear from the data bus. Addressing the \overline{LE} with a low static (Logic '0'), the latches become active and adapt the logic states present on the data bus. During this state, the output of the DAC will change to the value proportional to the data bus value. When the latch enable returns to a high state, the selected set of data inputs (i.e., depending on which \overline{LE} goes high) 'memorizes' the data bus logic states and the output changes to the unique output value corresponding to the binary word in the latch.

The data inputs are inactive and high impedance (typically requiring -2μ A for low (0.8V max) or 0.1μ A for high (2.0V min) when the \overline{LE} is high. Any changes on the data bus with \overline{LE} high will have no effect on the DAC output.

The digital logic inputs (\overline{LE} and DB) for the NE5020 utilize a differential input logic system with a threshold level of +1.4V with respect to the voltage level on the digital ground pin (Pin 1). Figure

10 details several bias schemes used to provide the proper threshold voltage levels for various logic families.

To be compatible with a bus-oriented system, the DAC should respond in as short a period as possible to insure full utilization of the microprocessor, controller and I/O control lines. Figure 9 shows the typical timing requirements of the latch and data lines. This figure indicates that data on the data bus should be stable for at least 50ns after \overline{LE} is changed to a high state.

The independent \overline{LE} (\overline{LE}_1 and \overline{LE}_2) lines allow for direct interface from an 8-bit bus (see Figure 11). Data for the two MSBs is supplied and stored when \overline{LE}_2 is activated low and returned high according to the NE5020 timing requirements. Then \overline{LE}_1 is activated low and the remaining eight LSBs of data are transferred into the DAC. With \overline{LE}_1 returning high, the loading of 10-bit data word from an 8-bit data bus is complete.

Occasionally the analog output must change to its data value within one data address operation. This is no problem using the NE5020 on a 16-bit bus or any other data bus with 10 or greater data bits.

This can be accomplished from an 8-bit data bus by utilizing an external latch circuit to pre-load the two MSB data values. Figure 12 shows the circuit configuration.

After pre-loading (via \overline{LE} pre-load) the external latch with the two MSB values, \overline{LE}_2 is activated low and the eight LSBs and the two MSBs are concurrently loaded into the DAC in one address operation. This permits the DAC output to make its appropriate change at one time.

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NE5020

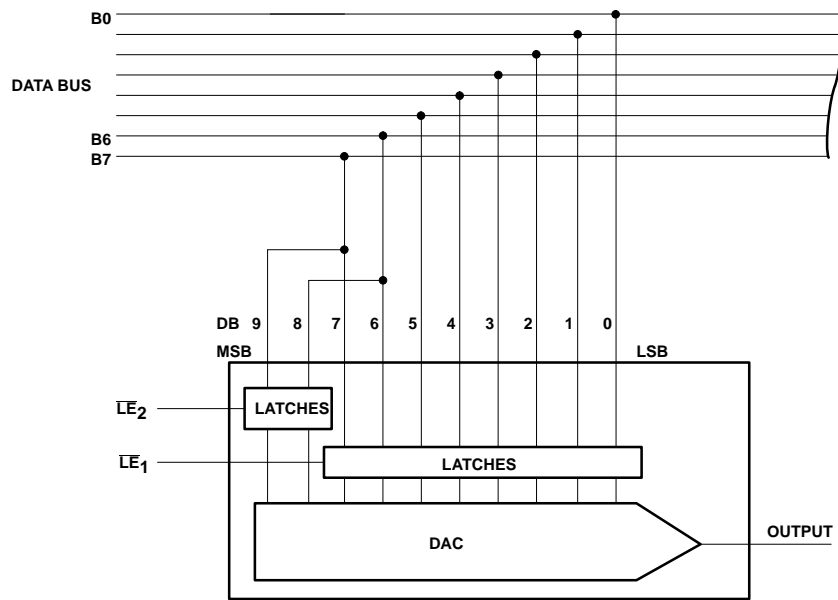


Figure 11. NE5020 μ P Interface 8-Bit Data Bus Example

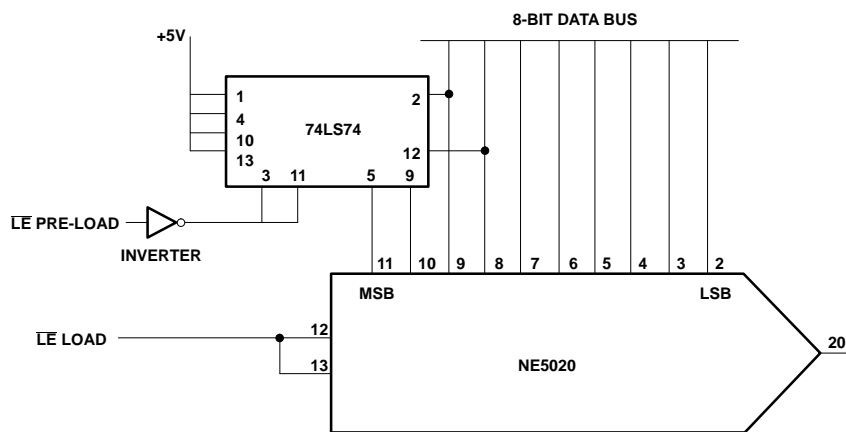


Figure 12. Pre-loading the 2 MSBs to Provide a Single-Step Output

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NE5020

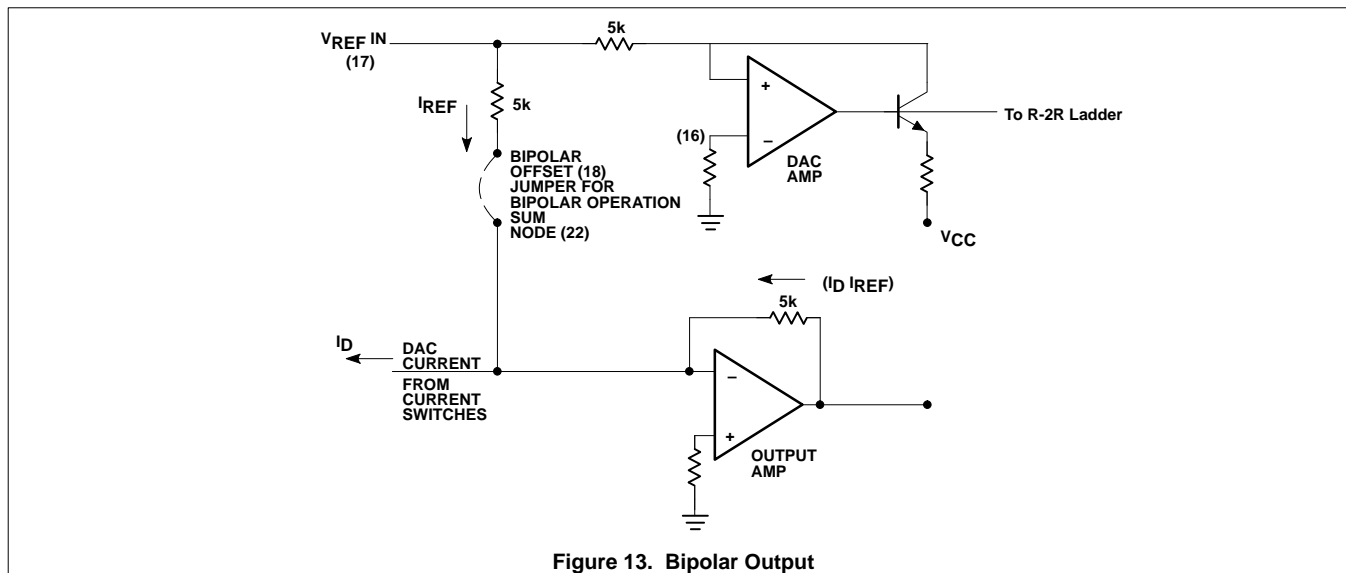


Figure 13. Bipolar Output

Reference Interface

The NE5020 contains an internal bandgap voltage reference which is designed to have a very low temperature coefficient and excellent long-term stability characteristics.

The internal bandgap reference (1.23V) is buffered and amplified to provide the 5V reference output. Providing a $V_{REF\ ADJ}$ (Pin 14) allows trimming of the reference output. Utilization of the adjust circuit shown in Figure 15 performs not only V_{REF} adjustment, but also full-scale output adjust. Notice that the $V_{REF\ ADJ}$ pin is essentially the sum node of an op amp and is sensitive to excessive node capacitance. Any capacitance on the node can be minimized by placing the external resistors as close as possible to the $V_{REF\ ADJ}$ pin and observing good layout

practices.

The $V_{REF\ OUT}$ node can drive loads greater than the DAC V_{REF} input requirements and can be used as an excellent system voltage reference. However, to minimize load effects on the DAC system accuracy, it is recommended that a buffer amplifier be used.

Input Amplifier

The DAC reference amplifier is a high gain internally-compensated op amp used to convert the input reference voltage to a precision bias current for the DAC ladder network.

The Block Diagram details the input reference amplifier and current ladder. The voltage-to-current converter of the DAC amp will generate a 1mA reference current through QR with a 5V V_{REF} . This current sets the input bias to the ladder network. Data bit 9 (DB9)(Q9), when turned on, will mirror this current and will contribute 1mA to the output. DB8 (Q8) will contribute 1/2 of that value or 0.5mA, and so on. These current values act as current sinks and will add at the sum node to produce a DAC ladder to sum node function of:

$$I_{OUT} = \frac{2V_{REF}}{R_{REF}} \left(\frac{DB9}{2} + \frac{DB8}{4} + \frac{DB7}{8} + \frac{DB6}{16} + \frac{DB5}{32} + \frac{DB4}{64} + \frac{DB3}{128} + \frac{DB2}{256} + \frac{DB1}{512} + \frac{DB0}{1024} \right)$$

Because of the fixed internal compensation of the reference amp, the slew rate is limited to typically 0.7V/ μ s and source impedance at the $V_{REF\ INPUT}$ greater than 5k Ω should be avoided to maintain stability.

The $-V_{REF\ INPUT}$ pin is uncommitted to allow utilization of negative polarity reference voltages. In this mode $+V_{REF\ INPUT}$ is grounded and the negative reference is tied directly to the $-V_{REF\ INPUT}$ contains a 5k Ω resistor that matches a like resistor in the $+V_{REF\ INPUT}$ to reduce voltage offset caused by op amp input bias currents.

Output Amplifier and Interface

The NE5020 provides an on-chip output op amp to eliminate the need for additional external active circuits. Its two-stage design with feed-forward compensation allows it to slew at 15V/ μ s and settle to within $\pm 1/2$ LSB in 5 μ s. These times are typical when driving the rated loads of $R_L \geq 5k$ and $C_L \leq 50pF$ with recommended values of $C_{FF} = 1nF$ and $C_{FB} = 30pF$. Typical input offset voltages of 5mV and 50k Ω open-loop gain insure that an accurate current-to-voltage conversion is performed when using the on-chip R_{FB} resistor. R_{FB} is matched to R_{REF} and R_{BIP} to maintain accurate voltage gain over operating conditions. The diode shown from ground to sum node prevents the DAC current switches from saturating the op amp during large signal transitions which would otherwise increase the settling time.

The output op amp also incorporates output short circuit protection for both positive and negative excursions. During this fault condition I_{OUT} will limit at $\pm 15mA$ typical. Recovery from this condition to rated accuracy will be determined by duration of short-circuit and die temperature stabilization.

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NE5020

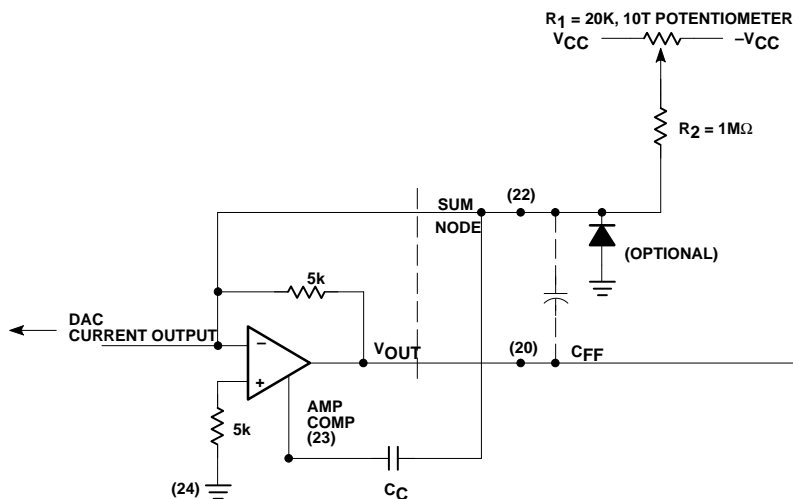


Figure 14. Zero-Scale Adjustment

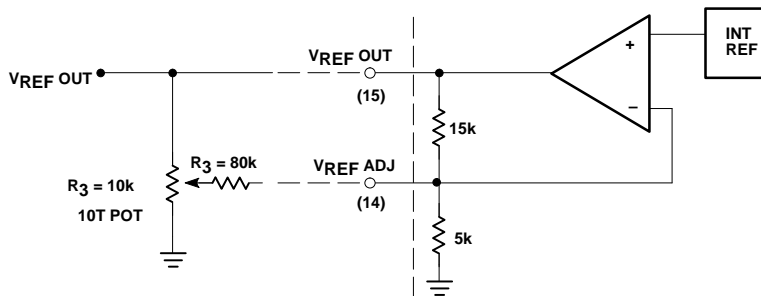


Figure 15. Reference Adjust Circuit

Bipolar Output Voltage

The NE5020 includes a thermally matched resistor, R_{BIP} , to offset the output voltage by 5V to obtain $-5V$ to $+5V$ output voltage range operation. This is accomplished by shorting Pins 18 and 22 (see Figure 13). This connection produces a current equal to $(V_{REFIN} - SUM\ NODE) \div R_{BIP}$ (1mA nominal), which is injected into the sum node. Since full-scale current out is approximately 2mA (1.9980mA), $(2mA - 1mA)5k\Omega = 5V$ will appear at the output. For zero DAC output currents, 1mA is still injected into sum node and $V_{OUT} = -(5k\Omega)(1mA) = -5V$. Zero-scale adjust and full-scale adjust are performed as described below, noting that full-scale voltage is now approximately +5V. Zero-scale adjust may be used to trim $V_{OUT} = 0.00$ with the MSB high or $V_{OUT} = -5.0V$ with all bits off.

Zero-Scale Adjustment

The method of trimming the small offset error that may exist when all data bits are low is shown in Figure 14. The trim is the result of injecting a current from resistor R_2 that counteracts the error current. Adjusting

potentiometer R_1 until V_{OUT} equals 0.000V in the unipolar mode or $-5.000V$ in the bipolar mode (see bipolar section accomplishes this trim).

Full-Scale Adjustment

A recommended full-scale adjustment circuit, when using the internal voltage reference, is shown in Figure 15. Potentiometer R_3 is adjusted until V_{OUT} equals 9.99023V. In many applications where the absolute accuracy of full-scale is of low importance when compared to the other system accuracy factors this adjustment circuit is optional.

As resistors R_{REF} , R_{FB} , and R_{BIP} shown in the Block Diagram are integrated in close proximity, they match and track in value closely over wide ambient temperature variations. Typical matching is less than $\pm 0.3\%$ which implies that typical full-scale (or gain) error is less than $\pm 0.3\%$ of ideal full-scale value.